

## ♦STRUCTURE

Silicon Monolithic Integrated Circuit

♦ PRODUCT SPI BUS 128Kbit (16,384 × 8bit) EEPROM

♦ PART NUMBER

# BR35H128-WC Series

PART NUMBER	PACKAGE
BR35H128F-WC	SOP8
BR35H128FJ-WC	SOP-J8

 ◇FEATURES Serial Peripheral Interface Single power supply (2.5V~5.5V) 1,000,000 erase/write cycles endurance (85°C) 500,000 erase/write cycles endurance (105°C) 300,000 erase/write cycles endurance (125°C)

# ◇ABSOLUTE MAXIMUM RATING (Ta=25°C)

Parameter	Symbol	Rating		Unit
Supply Voltage	Vcc	-0.3~6.5		V
Dower Dissipation	Pd	560 (BR35H128F-WC)	<b>※</b> 1	mW
Power Dissipation	Pu	560 (BR35H128FJ-WC)	Ж2	
Storage Temperature	Tstg	-65~150		°C
Operating Temperature	Topr	-40~125		°C
Terminal Voltage	_	-0.3~Vcc+0.3		V

 $Degradation is done at 4.5 mW/^{\circ}C(X1,2)$  for operation above 25°C.

# ◇RECOMMENDED OPERATING CONDITION

Parameter	Symbol	Rating	Unit
Supply Voltage	Vcc	2.5~5.5	V
Input Voltage	VIN	0~Vcc	v



#### ♦ MEMORY CELL CHARACTERISTICS(Vcc=2.5~5.5V)

Parameter			Specification		Unit	Test
Parameter		Min.	Typ.	Max.	Unit	Condition
		1,000,000	-	-	Cycle	Ta≦85°C
Write/Erase Cycle	*1	500,000	-	-	Cycle	Ta≦105℃
		300,000	-	-	Cycle	Ta≦125℃
Data Retention	*1	40	-	-	Year	Ta≦25°C
Data Retention	*1	20	-	-	Year	Ta≦125°C

OInitial Data: Memory array FFh

\*1 Not 100% TESTED

- -. .

## ♦ DC OPERATING CHARACTERISTICS

(Unless otherwise sp	pecified	Ta=-4	-0 <b>~</b>	125°C	, Vcc=	=2.5~5.5V)
Parameter	Svmbol	Specification		Unit	test condition	
Parameter	Min. Typ. Max.		Lest condition			
"H" Input Voltage	VIH1	0.7xVcc	Ι	Vcc+0.3	V	2.5V≦Vcc≦5.5V
"L" Input Voltage	VIL1	-0.3	Ι	0.3xVcc	V	2.5V≦Vcc≦5.5V
"L" Output Voltage	VOL	0	Ι	0.4	V	IOL=2.1mA (Vcc=2.5V~5.5V)
"H" Output Voltage	VOH	Vcc-0.5	Ι	Vcc	V	IOH=-0.4mA (Vcc=2.5V~5.5V)
Input Leakage Current	ILI	-10	-	10	μA	VIN=0V~Vcc
Output Leakage Current	ILO	-10		10	μA	VOUT=0V~Vcc,CSB=Vcc
	ICC1	-	-	2.5	mA	Vcc=2.5V , fSCK=5MHz , tE/W=5ms
Operating Current						Byte Write, Page Write
Write	ICC2		-	5.5	mA	Vcc=5.5V , fSCK=5MHz , tE/W=5ms
		_				Byte Write, Page Write
	ICC3	-	-	1.5	mA	Vcc=2.5V , fSCK=5MHz
Operating Current						Read, Read Status Register
Read	ICC4	-	-	2		Vcc=5.5V,fSCK=5MHz
					mA	Read, Read Status Register
						Vcc=5.5V
Standby Current	ISB	-	-	10	μA	CSB=Vcc
						SCK=SI=Vcc or GND, SO=OPEN
OThis product is	not des	igned 1	for p	rotect	tion ag	gainst

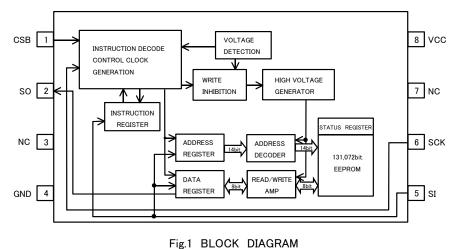
♦ AC OPERATING CHARACTERISTICS

(Unless otherwise s	specified	Ta=-40∼1	25°C,	C <sub>L</sub> =100	)pF)		
Parameter		Symbol	2.5V≦VCC≦5.5V		≦5.5V	Unit	
Parameter		Symbol	Min.	Typ.	Max.	Unit	
SCK clock Frequency		fSCK		-	5	MHz	
SCK High Time		tSCKWH	85	I		ns	
SCK Low Time		tSCKWL	85	Ι	-	ns	
CS High Time		tCS	85		Ι	ns	
CS Setup Time		tCSS	90	I		ns	
CS Hold Time		tCSH	85	Ι	-	ns	
SCK Setup Time		tSCKS	90		Ι	ns	
SCK Hold Time		tSCKH	90	I		ns	
SI Setup Time		tDIS	20	I	_	ns	
SI Hold Time		tDIH	30	Ι	-	ns	
Output Data Delay Time	1	tPD1	I	I	70	ns	
Output Data Delay Time2	(CL=30pF)	tPD2	I	Ι	55	ns	
Output Hold Time		tOH	0	-	I	ns	
Output Disable Time		tOZ	I	Ι	100	ns	
SCK Rise Time	*1	tRC	I	I	1	μs	
SCK Fall Time	*1	tFC	_	_	1	μs	
Output Rise Time	*1	tRO	I	-	50	ns	
Output Fall Time	*1	tFO	-	_	50	ns	
Write Cycle Time		tE/W	-	_	5	ms	
		v		100%		-	

radioactive rays.

※1 Not 100% TESTED

# ♦BLOCK DIAGRAM



# ♦PIN No. / PIN NAME

PIN NAME
CSB
SO
NC
GND
SI
SCK
NC
VCC



#### NOTES FOR POWER SUPPLY

In order to prevent an inadvertent write, the device has the feature of P.O.R.

After the power is on, the device is in the write disable mode. P.O.R. works only during power up. The noise may force the device write enable mode with CSB="H" during power ON/OFF. In the case of power up, keep the following conditions to ensure to make the function of P.O.R.

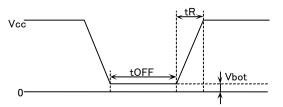


Fig.2 Vcc Waveform

### RECOMMENDED CONDITIONS OF tR, tOFF, Vbot

tR	tOFF	Vbot
Below 10ms	Above 10ms	Below 0.3V
Below 100ms	Above 10ms	Below 0.2V

Please keep CSB "H" during power ON/OFF.

The device is an active state during CSB is low. The extraordinary function or data collaption may occur because of noise etc., if power-up is done with CSB "L". In order to prevent above errors from happening, keep CSB "H" (=Vcc) during power ON. (The device does not receive any command during CSB is high.)

It may continue at low Vcc by capacitance of Vcc line during power off.

Please keep CSB "H" during power off because of the device may make malfunction and inadvertent write.

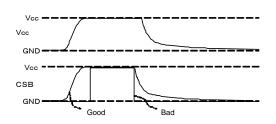


Fig.3 CS TIMING DURING POWER ON/OFF

(Good example) CSB follows Vcc. (CSB is pull up to Vcc)

(Bad example)

CSB is low during power ON/OFF.

Please take more than 10ms between power ON and power OFF, or the internal circuit is not always reset.

#### ♦ CAUTIONS ON USE

(1) Absolute maximum ratings

If the absolute maximum ratings such as impressed voltage and operating temperature range and so forth are exceeded, LSI may be destructed. Do not impress voltage and temperature exceeding the absolute maximum ratings. In the case of fear exceeding the absolute maximum ratings, take physical safety countermeasures such as fuses, and see to it that conditions exceeding the absolute maximum ratings should not be impressed to LSI.

(2) GND electric potential

Set the voltage of GND terminal lowest at any action condition. Make sure that each terminal voltages is lower than that of GND terminal.

(3) Heat design

In consideration of permissible dissipation in actual use condition, carry out heat design with sufficient margin.

(4) Terminal to terminal shortcircuit and wrong packaging

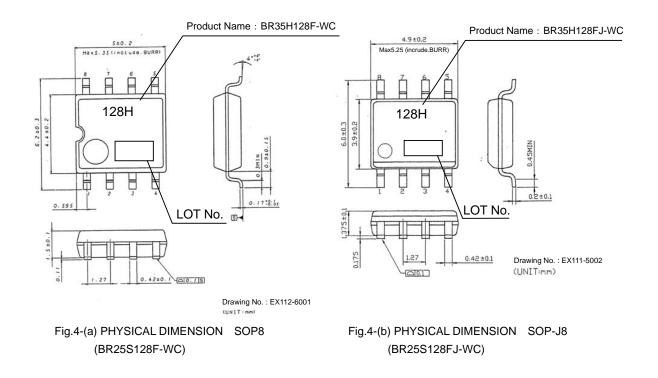
When to package LSI onto a board, pay sufficient attention to LSI direction and displacement. Wrong packaging may destruct LSI. And in the case of shortcircuit between LSI terminals and terminals and power source, terminal and GND owing to foreign matter, LSI may be destructed.

(5) Strong electromagnetic field

Use in a strong electromagnetic field may cause malfunction, therefore, evaluated design sufficiently.



# ♦ PHYSICAL DIMENSION



REV. B

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